

RoHS Compliant Product  
A suffix of "-HF" specifies halogen & lead-free

### DESCRIPTION

The STESD12-C is designed to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time provide best in class protection on designs that are exposed to ESD. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and many other portable applications where board space is at a premium.

### APPLICATIONS

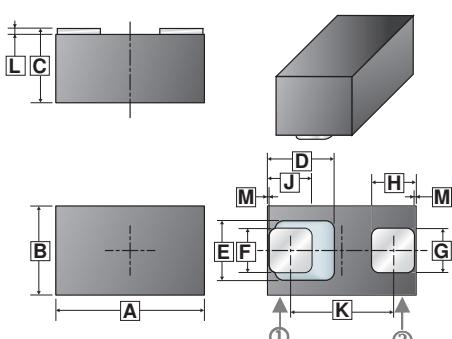
- Stand-off Voltage: 12V
- Low Leakage
- Response Ttime Is Typically<1Ns
- ESD Rating of Class 3 (>16kv) Per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection

### MARKING



### PACKAGE INFORMATION

Package	MPQ	Leader Size
WBFBP-02C	10K	7 inch



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	0.95	1.05	G	0.25	0.35
B	0.55	0.65	H	0.25	0.35
C	0.44	0.55	J	0.275	0.47
D	0.470 REF.		K	0.555	0.725
E	0.420 REF.		L	0.010	0.100
F	0.27	0.37	M	0.030 REF.	

### ORDER INFORMATION

Part Number	Type
STESD12-C	Lead (Pb)-free and Halogen-free



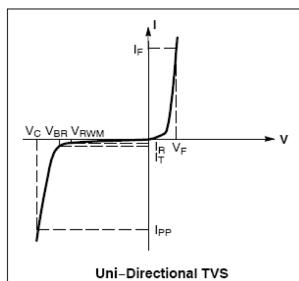
### MAXIMUM RATINGS ( $T_A=25^\circ\text{C}$ unless otherwise noted.)

Parameter	Symbol	Ratings	Unit
IEC 61000-4-2 (ESD)	Contact	±30	kV
ESD Voltage		16	kV
		400	V
Total Power Dissipation on FR-5 Board <sup>1</sup>	P <sub>D</sub>	100	mW
Thermal Resistance Junction-Ambient	R <sub>θJA</sub>	1250	°C/W
Lead Solder Temperature-Maximum (10 Second Duration)	T <sub>L</sub>	260	°C
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55~150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Note:

1. FR-5=1.0 x 0.75 x 0.62 in.

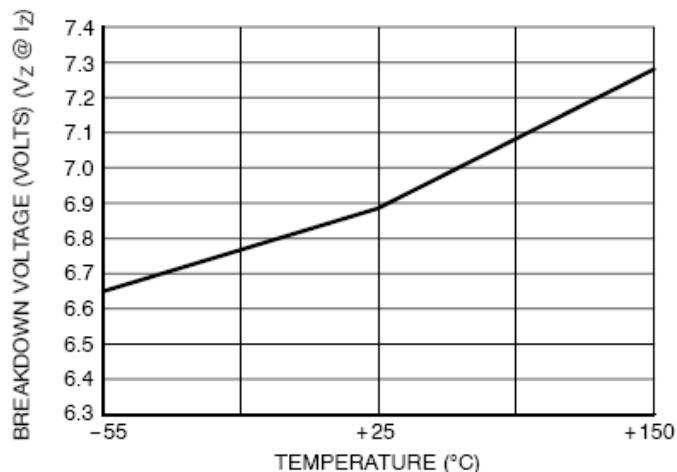
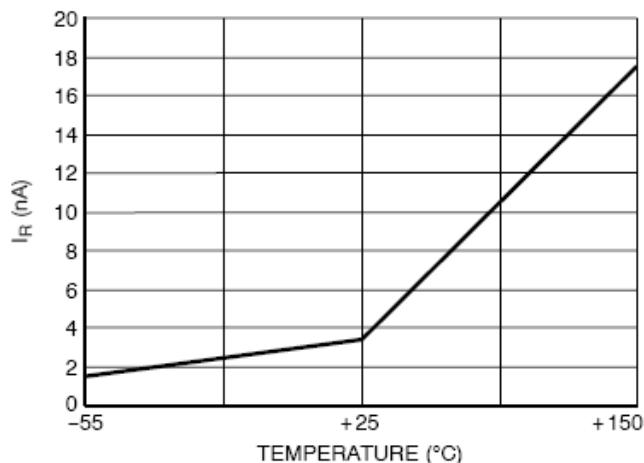
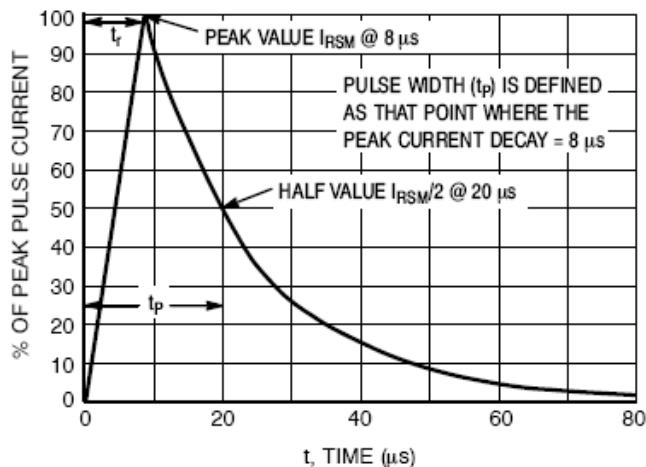


**ELECTRICAL CHARACTERISTICS** ( $T_A=25^\circ\text{C}$  unless otherwise noted.)

Parameter	Symbol	Min.	Typ.	Max.	Unit
Working Peak Reverse Voltage	$V_{RWM}$	-	-	12	V
Maximum Reverse Leakage Current @ $V_{RWM}$	$I_R$	-	-	1.0	$\mu\text{A}$
Breakdown Voltage @ $I_T^2$	$V_{BR}$	13.5	-	15.6	V
Test Current	$I_T$	-	-	1.0	mA
Maximum Reverse Peak Pulse Current <sup>3</sup>	$I_{PP}$	-	-	5.9	A
Clamping Voltage @ $I_{PP}^3$	$V_C$	-	-	23.7	V
Peak Power Dissipation (8X20 $\mu\text{s}$ )	$P_{PK}$	-	140	-	W
Max. Capacitance @ $V_R=0$ and $f=1\text{MHz}$	C	-	30	-	pF

Notes:

2.  $V_{BR}$  is measured with a pulse test current  $I_T$  at an ambient temperature of  $25^\circ\text{C}$ .  
 3. Surge current waveform per Figure 3.

**CHARACTERISTICS CURVES**

**Figure 1. Typical Breakdown Voltage versus Temperature**

**Figure 2. Typical Leakage Current versus Temperature**

**Figure 3. 8 X 20  $\mu\text{s}$  Pulse Waveform**